

28. The ceramic/metal substrate according to claim 27, wherein metal surfaces of the substrate areas are formed by at least one textured or structured metalization on at least one surface area of the ceramic layer.

29. The ceramic/metal substrate according to claim 28, wherein the at least one textured or structured metalization is produced by applying a metal layer or metal foil by a heating process, selected from the group consisting of direct copper bonding and an active soldering.

30. The ceramic/metal substrate according to claim 27, wherein at least part of the substrate areas are single substrates.

31. The ceramic/metal substrate according to claim 27, wherein the width (a) of the edge reduction or of the reduced metal mass area is approximately 0.2 to 6 mm.

32. The ceramic/metal substrate according to claim 27, wherein at least one outer metal surface that is provided for on at least one surface of the ceramic layer at least along one edge of the ceramic/metal substrate, and by at least one predetermined break line between the at least one outer metal surface and adjacent substrate areas, whereby the at least one outer metal surface has an edge reduction along the predetermined break line.

33. The ceramic/metal substrate according to claim 27, wherein an edge having the edge reduction has a distance (d_1, d_2) from the adjacent predetermined break line or a plane (SE) of the predetermined break line that is considerably less than 1 mm.

34. The ceramic/metal substrate according to claim 27, wherein edges with the edge reduction have a distance from the respective predetermined break line of approximately 0.05 to 1 mm.

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35. The ceramic/metal substrate according to claim 28, wherein the textured or structured metalizations, or metal surfaces formed by these, have a thickness of between approximately 0.15 to 1 mm.

36. The ceramic/metal substrate according to claim 27, wherein the edge reduction is formed by beveling of the respective edge, the beveling forms an angle smaller than 45° with a plane of the ceramic layer.

37. The ceramic/metal substrate according to claim 27, wherein the edge reduction is formed by hollows or depressions in a material of the metal surface.

38. The ceramic/metal substrate according to claim 37, wherein the hollows or depressions are formed continuously, and extend to a surface side of the ceramic layer adjacent to the metal surface.

39. The ceramic/metal substrate according to claim 37, wherein the hollows or depressions are formed in such a way that metal from the metal surface remains on the surface side of the ceramic layer adjacent to the metal surface.

40. The ceramic/metal substrate according to claim 27, wherein the edge reduction is formed by a number of hole-like depressions that are arranged as a row of holes.

41. The ceramic/metal substrate according to claim 40, wherein outer and inner depressions form an outer and a second inner row of holes.

42. The ceramic/metal substrate according to claim 40, wherein the depressions have a diameter of approximately 0.5 to 0.6 mm.

~~43. The ceramic/metal substrate according to claim 40, wherein the depressions forming a single row of holes have a diameter of 0.5 mm, with a width of the edge reduction of approximately 0.8 mm and with a distance of the edge from the predetermined break line of approximately 0.5 mm.~~

44. The ceramic/metal substrate according to claim 40, wherein the several rows of holes of the outer row of holes have a diameter that is larger than a diameter of the depressions of the inner row of holes, whereby the diameter of the depressions of the outer row of holes is approximately 0.6mm and the diameter of the depressions of the inner row of holes is approximately 0.4 mm and the width of the edge reduction is approximately 1.4 mm.

45. The ceramic/metal substrate according to claim 27, wherein the edge reduction is formed by a groove-shaped depression.

46. The ceramic/metal substrate according to claim 27, wherein the edge reduction is formed by a graduation in at least one partial area.

47. The ceramic/metal substrate according to claim 27, wherein at least in an area of the single substrate on both surfaces of the ceramic layer at least one metal surface is provided for and that the at least one metal surface has, on a first surface area, on a bottom of the ceramic/metal substrate, an edge distance (d_1) from the adjacent predetermined break line or its plane which edge distance is smaller than the edge distance (d_2) of the metal surfaces on the second surface area, on a top of the ceramic/metal substrate.

48. The ceramic/metal substrate according to claim 27,
wherein with several substrate areas or single substrates

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CONT.*

arranged in several rows, two groups of crossing predetermined break lines are formed.

49. The ceramic/metal substrate according to claim 27, wherein on at least one surface area of the ceramic/metal substrate, all edges of the metal surfaces adjacent to a predetermined break line are provided with edge reduction.

50. The ceramic/metal substrate according to claim 27, wherein the metal surfaces on at least one surface area of the ceramic layer has no edge reduction on edges that are adjacent to a group of predetermined break lines.

51. The ceramic/metal substrate according to claim 27, wherein the single substrates formed by substrate areas are not provided with components.

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52. The ceramic/metal substrate according to claim 27, wherein the single substrates formed by substrate areas are provided with electric components.--

REMARKS

Applicant has amended the claims to coincide with U.S. Patent Practice inserting necessary section headings and the like. A certified copy of the priority document, German Application No. 199 27 046.5 dated June 14, 1999 will be forwarded at a later date. An English translation of the German application is enclosed along with a marked-up copy of the Specification and a clean "Substitute Specification". Further, applicant has cancelled claims 1-26 and inserted replacement claims 27-52 to more accurately comply with U.S. examination procedures. Multiple dependencies have been removed from the claims. By both amendment of the specification and claims, no new matter has been inserted into the application.